

**Remarks/Arguments:**

The Abstract of the disclosure has been objected to. The Abstract has been replaced. Withdrawal of the rejection is respectfully requested.

The Title was found to be non-descriptive. A new title has been furnished.

Claims 13-46 have been rejected under 35 U.S.C. §112, second paragraph. Regarding claim 13, this claim has been appropriately amended. Regarding claim 14, the Official Action had many questions regarding the phrase "electroconductive rubber piece." In response, enclosed is the result of an internet search that identified Yokohama Rubber, a company that makes conductive rubber. Also, various phrases in claims 20, 35, and 46 were found to be unclear. These phrases have been appropriately amended. Withdrawal of the rejection is respectfully requested.

Claim 13 has been rejected under 35 U.S.C. §102(b) as being anticipated by JP 8-335605. In making this rejection, the Official Action relied on U.S. Patent No. 5,816,478. It is respectfully submitted, however, that this claim is patentable over the art of record for the reasons set forth below.

Applicants' invention, as recited by claim 13, includes a feature which is neither disclosed nor suggested by the art of record, namely:

. . . printing an electroconductive adhesive . . .  
. . . connecting an electrode . . . to said electroconductive adhesive . . .  
. . . drying said adhesive at a temperature of 50°-120°C.

This feature is supported by the originally filed application at page 21, line 18. No new matter has been added. According to Applicants' claimed invention, an electroconductive adhesive is dried in order to connect an electrode to a connecting area. This is different than the '605 Patent where a permanent bond is created by reflow of solder ball 12. Accordingly, Applicants' claim 13 is patentable over the prior art.

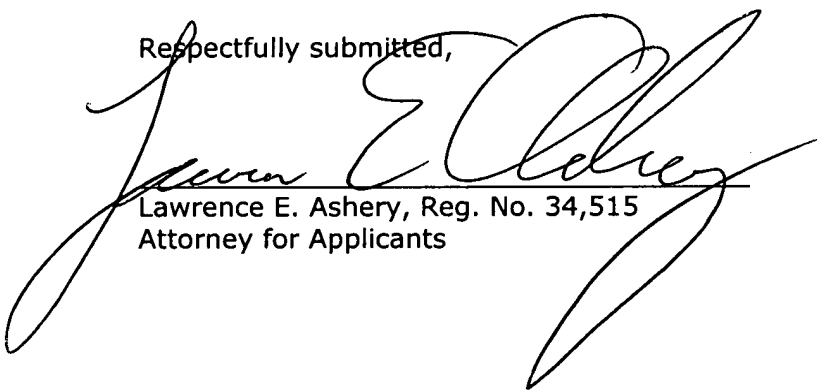
Appln. No.: 09/195,595  
Amendment Dated: April 14, 2004  
Reply to Office Action of: January 26, 2004

MAT-6750US

Claim 16 has been rejected under 35 U.S.C. §103(a) based upon certain cited prior art. This claim, as well as all the other pending claims, are patentable by virtue of their dependency on allowable claim 13.

In view of the amendments and arguments set forth above, the above identified application is in condition for allowance which action is respectfully requested.

Respectfully submitted,

  
Lawrence E. Ashery, Reg. No. 34,515  
Attorney for Applicants

LEA:ds

Enclosure: Internet Search Result

Dated: April 14, 2004

P.O. Box 980  
Valley Forge, PA 19482  
(610) 407-0700

The Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 18-0350 of any fees associated with this communication.

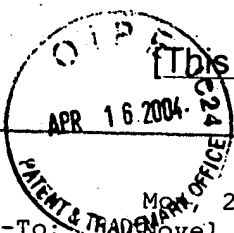
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

April 14, 2004

DS\_I:\MAT\6750\AMEND\_01.DOC

**ABSTRACT**

A method of manufacturing an electronic component unit comprises the steps of forming a conductive pattern on a surface of a substrate, roughening a surface of a connecting area of said conductive pattern, printing an adhesive on the connecting area, connecting an electrode of an electronic component to the electroconductive adhesive on the connecting area, and drawing the adhesive at a temperature of 50-120° C.



[This Month] [Other Months] [Search] [Biomch-L Home]

Date: Mon, 28 Aug 1995 09:39:41 EDT  
Reply-To: Novel Biomechanics Lab <100607.2101@COMPUSERVE.COM>  
Sender: Biomechanics and Movement Science listserver  
<BIOMCH-L@NIC.SURFNET.NL>  
From: Novel Biomechanics Lab <100607.2101@COMPUSERVE.COM>  
Subject: Summary re. conductive rubber

Dear BIOMCHERS!

As is usual practice I enclose a brief summary of the information that I was sent regarding my enquiry about conductive rubber whose electrical resistance varies according to the applied pressure.

I apologise for the delay in posting this summary, but having returned from holiday I found that my CServe software now refused to work and I lost the stored messages. Hence the slightly brief version of this summary.

My original message was:

Dear BIOMCH-L

I am interested in finding out the address of the company Yokohama (I think) who manufacture a conductive rubber whose electrical resistance varies according to the applied pressure.

If anybody out there has either used this rubber or can give me the address of the supplier, I would be very grateful.

Thanks in advance

Anna Hayes

#### SUMMARY OF RESPONSES:

Several people sent me addresses, telephone numbers and contact info. Thank you for those.

Several people said they hadn't used this rubber themselves but would be interested in the responses to my query. This is for you!

1. Yokohama toll free support number: 800/423-4544
2. Kai An at [an.kainan@mayo.edu](mailto:an.kainan@mayo.edu) used this material to measure the wrist joint pressure (J. Hand Surgery 17A 339-347, 1992) and suggested to contact Prof. Toshiaki Hara at Niggata University, Japan, Dept. of ME. Fax: 81-025-261-3563 for general information.
3. Christian Calame at [100072.1173@compuserve.com](mailto:100072.1173@compuserve.com) suggested contacting Dr. Shohi Morimoto at [morimoto@eirec3.lwc-eirec.go.jp](mailto:morimoto@eirec3.lwc-eirec.go.jp) who is a skilled user of conductive rubbers.
4. James Moore at [moore@lwc-eirec.go.jp](mailto:moore@lwc-eirec.go.jp) gave me the Japanese address:

Yokohama Rubber

Overseas Sales  
Attn. Mr. Yamamoto  
6-1-11 Shinbashi  
Minato Ku, Tokyo 105  
Tel: +81(3)5400-4816  
Fax: +81(3)5400-4830

He suggests that their spoken English is not so good, and that it would be best to fax them.

5. Joseph Hale at [jhale@virginia.edu](mailto:jhale@virginia.edu) gave me another address:

The Yokohama Rubber CO., Ltd.  
Hiratsuka Plant  
M.B. Technical Development Center  
2-1 Oiwake, Hiratsuka  
Kanagawa 254, JAPAN

Thank you to everybody that responded.

Anna Hayes

---

[\[This Month\]](#) [\[Other Months\]](#) [\[Search\]](#) [\[Biomch-L Home\]](#)